<<TITEL>>

<<Name>>1, <<Name>>2

1 <<Company 1>>
2 <<Company 2>>

Presenter: <<Name of Presenter>>
E-mail: <<email>>

Presentation (oral and/or poster):

TOPIC:
Please select one or more fitting topic(s) for your contribution from the list. (1=first, 2=second etc. choice)

|  |  |  |
| --- | --- | --- |
| Process Level APC🗆 Plasma etch,CVD and ALD🗆 Sputtering, P3I, and e--beam🗆 Lithography🗆 Thermal, wet processing & CMP🗆 Backend🗆 Metrology and R2R🗆 APC for legacy tools | Fab Level APC🗆 Fab level process control methods🗆 Virtual metrology🗆 Yield management🗆 Factory data analysis🗆 IT infrastructure | Manufacturing Effectiveness and Productivity🗆 Unit process & equipment productivity🗆 Factory productivity and automation🗆 Factory modeling, simulation and optimization🗆 Cost optimization and end-of-life equipment issues🗆 Environment and Green Manufacturing |

## Motivation

<<TEXT>>

## Description

<<TEXT>>

## Innovation

<<TEXT>>

## Results

<<TEXT>>